

Amendments to the Claims

1. (Previously Presented) A method for opening an integrated circuit fuse, the method comprising the steps of:

generating at least one opening to a fuse element that couples a plurality of terminals and is located in a non-last metal layer; and

wet etching the fuse element to open the fuse.
2. (Original) The method of claim 1, wherein the generating step includes:

applying a photoresist to define an opening area for each opening; and

etching to generate the at least one opening.
3. (Original) The method of claim 2, wherein the applying step includes:

depositing the photoresist;

exposing the photoresist using laser light; and

developing the photoresist to define the opening area for each opening.
4. (Original) The method of claim 3, wherein the generating step further includes removing the photoresist and a diffusion barrier on the fuse element.
5. (Original) The method of claim 1, wherein the generating step includes applying a polymer and ablating the polymer with a laser to define the at least one opening.

6. (Cancelled).

7. (Original) The method of claim 1, wherein the at least one opening includes one opening to each side of the plurality of terminals.

8. (Original) The method of claim 7, wherein the wet etching step removes the fuse element under the plurality of terminals.

9. (Original) The method of claim 1, wherein each terminal is fully-landed on a wire of the fuse element and includes a metal liner surrounding the terminal.

10. (Original) The method of claim 1, wherein the fuse element and each terminal include copper.

11. (Original) The method of claim 1, wherein the wet etchant includes at least one of sulfuric acid, aqueous ammonium persulfate, hydrogen peroxide and water.

12. – 30. (Cancelled)